



Device Type: Q6C LFBGA_256_17x17x1.7_SnPB				Package Homogeneous Materials				
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	(mg) Total	% of Total Weight	
Epoxy Resin A	Trade Secret	Mold Compound	2.687	25.970	26.871	346.22	35.82	
Epoxy Resin B	Trade Secret	Mold Compound	1.970	19.040	19.701			
Phenol Resin	9003-35-4	Mold Compound	1.075	10.390	10.750			
Silica ( Amorphous) A	60676-86-0	Mold Compound	24.359	235.420	243.587			
Silica ( Amorphous) B	7631-86-9	Mold Compound	2.687	25.970	26.871			
Metal Hydroxide	Trade Secret	Mold Compound	1.075	10.390	10.750			
Carbon Black	1333-86-4	Mold Compound	1.970	19.040	19.701			
Copper	7440-50-8	Solder Mask	3.448	33.32	34.476			
Copper	7440-50-8	Solder Mask	3.448	33.320	34.476			
Nickel	7440-02-0	Solder Mask	1.806	17.450	18.055	117.79	12.19	
Gold	7440-57-5	Solder Mask	0.410	3.960	4.097			
Copper	7440-50-8	Solder Mask	3.077	29.740	30.772			
Thermosetting Resin	Trade Secret	Resin A	6.686	64.620	66.862			
Glass cloth	65997-17-3	Resin A	4.457	43.080	44.575			
Cured Thermosetting Resin	Trade Secret	Resin B	2.318	22.400	23.177			
Glass Wool	65997-17-3	Resin B	2.318	22.400	23.177			
Copper	7440-50-8	Resin B	2.841	27.460	28.413			
Morpholine Derivative	Trade Secret	Acrylate Ester Resin	0.491	4.750	4.915	57.71	5.97	
Barium Sulfate	7727-43-7	Acrylate Ester Resin	5.651	54.620	56.515			
Silica	7631-86-9	Acrylate Ester Resin	0.123	1.190	1.231			
Talc	1480796-6	Acrylate Ester Resin	0.491	4.750	4.915			
Dipropylene Glycol Monomethyl Ether	34590-94-8	Acrylate Ester Resin	2.949	28.500	29.489	107.70	11.14	
Epoxy Resin	85954-116	Acrylate Ester Resin	3.098	29.940	30.979			
Silicon	7440-21-3	Die	5.971	57.710	59.712			
Silver	7440-22-4	Epoxy	0.724	7.000	7.243			
Neopentanediol dimethacrylate	1985-51-9	Epoxy	0.048	0.460	0.476			
Epoxy Resin	Trade Secret	Epoxy	0.048	0.460	0.476	72.26	7.48	
Methacrylate Resin	Trade Secret	Epoxy	0.048	0.460	0.476			
Copper	7440-50-8	Wire	0.793	7.660	7.926			
Palladium	7440-05-3	Wire	0.012	0.120	0.124			
Gold	7440-57-5	Wire	0.001	0.010	0.010			
Tin	7440-31-5	Solder Ball	8.159	78.850	81.586			
Lead	7439-92-1	Solder Ball	4.762	46.020	47.617	8.38	0.87	
<b>966.47 mg Total Mass</b>			<b>TOTALS:</b>	<b>100.00</b>	<b>966.47</b>	<b>1,000.000</b>		
							<b>100.00</b>	
							<b>7.48</b>	
							<b>31.00</b>	
							<b>31.00</b>	
							<b>38.00</b>	
							<b>100.00</b>	
							<b>83.53</b>	
							<b>5.49</b>	
							<b>5.49</b>	
							<b>5.49</b>	
							<b>100.00</b>	
							<b>0.81</b>	
							<b>98.33</b>	
							<b>1.54</b>	
							<b>0.13</b>	
							<b>100.00</b>	
							<b>12.92</b>	
							<b>63.1</b>	
							<b>36.85</b>	
							<b>100.00</b>	
							<b>12.80</b>	
							<b>3.84</b>	
							<b>44.14</b>	
							<b>0.96</b>	
							<b>3.84</b>	
							<b>23.03</b>	
							<b>24.19</b>	
							<b>100.00</b>	
							<b>100.00</b>	

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at <http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/>

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <http://echa.europa.eu/web/guest/candidate-list-table>